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WPI Acc No: 2002-086347/200212

XRAM Acc No: C02-026726

XRPX Acc No: N02-064235

Inorganic board manufacture, for use as coverings and tiles for buildings, involves applying sealant to hydraulic material containing cement, before curing

Patent Assignee: MATSUSHITA ELECTRIC WORKS LTD (MATW )

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 2001300924	A	20011030	JP 2000121682	A	20000421	200212 B

Priority Applications (No Type Date): JP 2000121682 A 20000421

Patent Details:

Patent No	Kind	Lan Pg	Main IPC	Filing Notes
JP 2001300924 A		3	B28B-011/04	

Abstract (Basic): JP 2001300924 A

NOVELTY - Hydraulic material containing cement as main component, is cured to form inorganic board. A sealant is applied to the material at a rate of 0.3-0.8 g/30 cm<sup>2</sup>, before curing.

USE - For manufacturing inorganic board used as coverings and tiles for buildings.

ADVANTAGE - The inorganic board has excellent coating film adhesion property. Blocking and generation of efflorescence, are prevented.

pp; 3 DwgNo 0/0

Technology Focus:

TECHNOLOGY FOCUS - POLYMERS - Preferred Sealant: The sealant contains acrylic type polymer, as main component.

Title Terms: INORGANIC; BOARD; MANUFACTURE; COVER; TILE; BUILD; APPLY; SEAL; HYDRAULIC; MATERIAL; CONTAIN; CEMENT; CURE

Derwent Class: A93; P64

International Patent Class (Main): B28B-011/04

International Patent Class (Additional): B28B-011/24

File Segment: CPI; EngPI

Manual Codes (CPI/A-N): A99-A

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